ELECTRICAL CHARACTERISTICS (Ambient Temperature = 25°C unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward Voltage	V_F	I_F = 20mA		1.2	1.4	V
Reverse Voltage	V_R	I_R = 10µA	6.0			V
Reverse Leakage	I_R	V_R = 4V			10	µA
Terminal Capacitance	C_t	V = 0V, f = 1KHz		30	250	pF

OUTPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Collector—Emitter Breakdown Voltage	BV_{CEO}	I_C = 1mA, I_F = 0mA	80			V
Emitter—Collector Breakdown Voltage	BV_{ECO}	I_E = 100µA, I_F = 0mA	6			V
Collector-Emitter Dark Current	I_{CEO}	V_{CE} = 20V, I_F = 0mA			100	nA

COUPLED

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Current transfer ratio	CTR	I_F = 5mA, V_{CE} = 5V Optional CTR Grades GR L (PS2501-1 only)	80 100 200		600 300 400	%
Collector—Emitter Saturation Voltage	$V_{CE(sat)}$	I_F = 10mA, I_C = 2mA			0.3	V
Input to Output Isolation Voltage	V_{ISO}	AC 1 minute, RH = 40 to 60% Note 1	5300			V_{RMS}
Input to Output Isolation Resistance	R_{ISO}	V_{IO}= 500V Note 1	$5x10^{10}$			Ω
Output Rise Time	t_r	V_{CE} = 2V, Ic = 2mA, R_L = 100Ω		4	18	µs
Output Fall Time	t_f	V_{CE} = 2V, Ic = 2mA, R_L = 100Ω		3	18	µs

Note 1 : Measure with input leads shorted together and output leads shorted together.

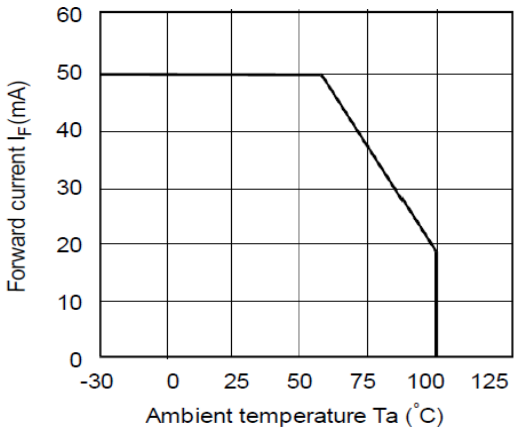


Fig 1 Forward Current vs T_A

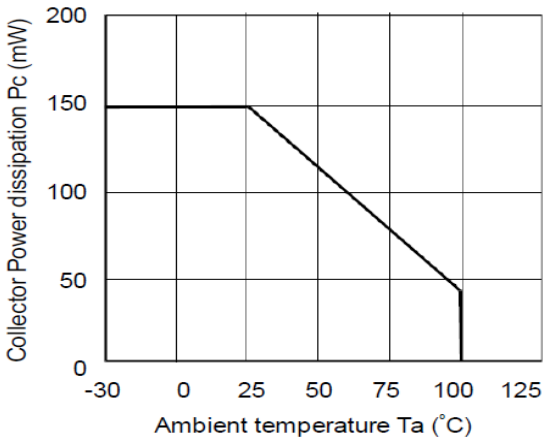


Fig 2 Collector Power Dissipation vs T_A

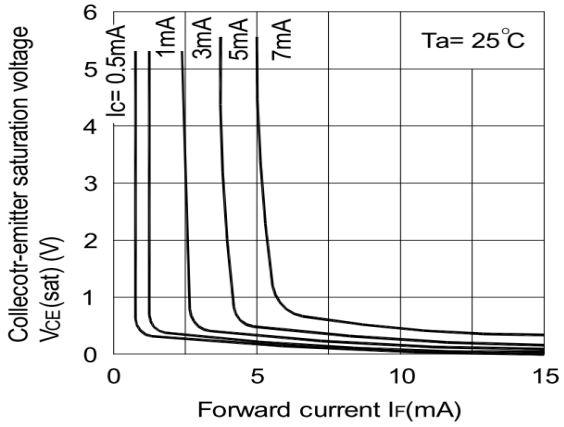


Fig 3 Collector-emitter Saturation Voltage vs Forward Current

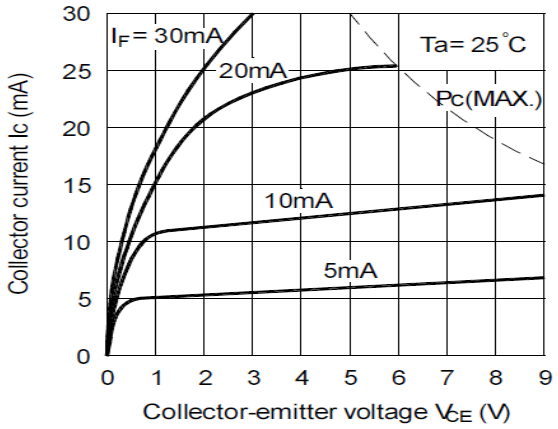


Fig 4 Collector Current vs Collector-emitter Voltage

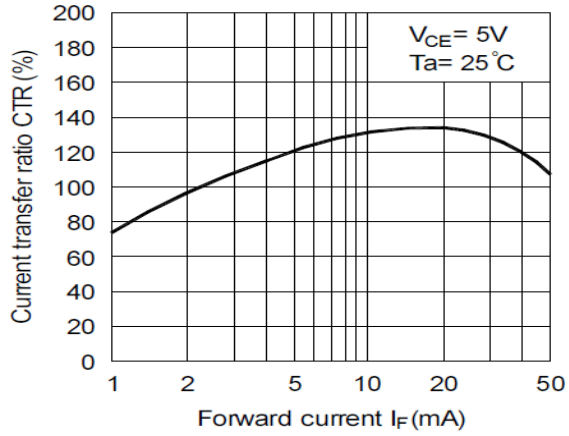


Fig 5 Current Transfer Ratio vs Forward Current

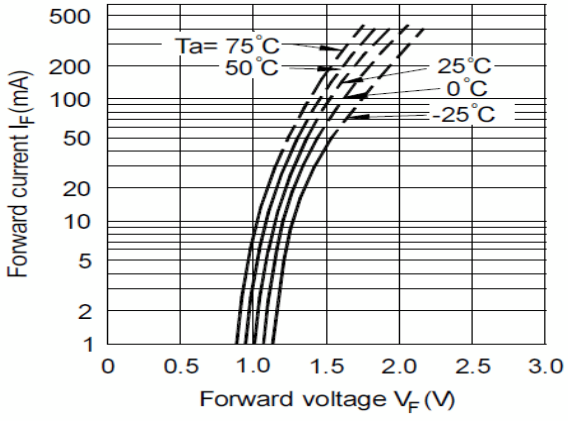


Fig 6 Forward Current vs Forward Voltage

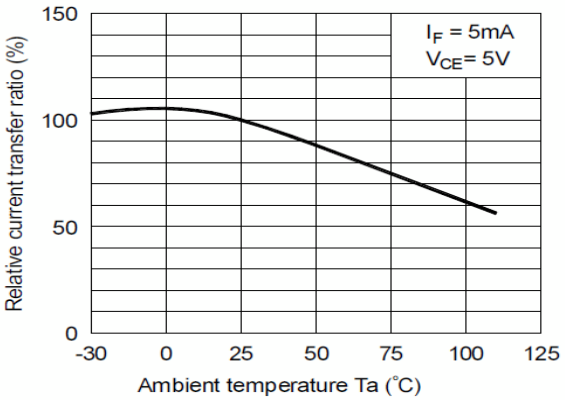


Fig 7 Relative CTR vs T_A

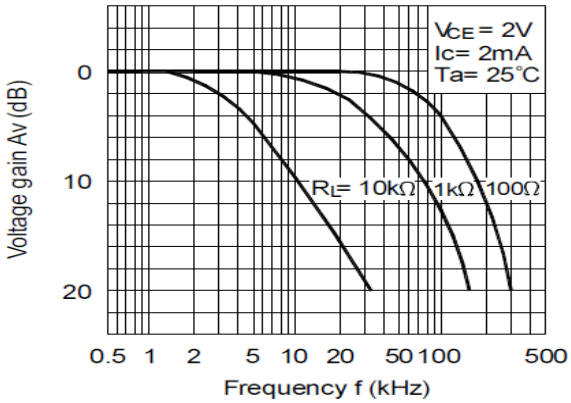


Fig 8 Frequency Response

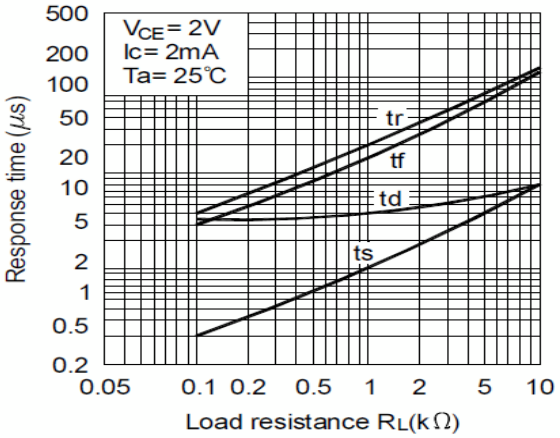
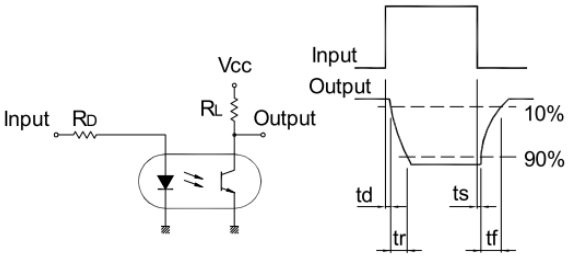


Fig 9 Response Time vs Load Resistance



Response Time Test Circuit

ORDER INFORMATION

PS2501-1 (UL Approval)			
After PN	**PN**	**Description**	**Packing quantity**
None	PS2501-1, PS2501-1GR, PS2501-1L	Standard DIP4	100 pcs per tube
G	PS2501-1G, PS2501-1GRG, PS2501-1LG	10mm Lead Spacing	100 pcs per tube
SM	PS2501-1SM, PS2501-1GRSM, PS2501-1LSM	Surface Mount	100 pcs per tube
SMT&R	PS2501-1SMT&R, PS2501-1GRSMT&R, PS2501-1LSMT&R	Surface Mount Tape & Reel	1000 pcs per reel

PS2501-2 (UL Approval)			
After PN	**PN**	**Description**	**Packing quantity**
None	PS2501-2, PS2501-2GR	Standard DIP8	50 pcs per tube
G	PS2501-2G, PS2501-2GRG	10mm Lead Spacing	50 pcs per tube
SM	PS2501-2SM, PS2501-2GRSM	Surface Mount	50 pcs per tube
SMT&R	PS2501-2SMT&R, PS2501-2GRSMT&R,	Surface Mount Tape & Reel	1000 pcs per reel

PS2501-4 (UL Approval)			
After PN	**PN**	**Description**	**Packing quantity**
None	PS2501-4, PS2501-4GR	Standard DIP16	25 pcs per tube
G	PS2501-4G, PS2501-4GRG	10mm Lead Spacing	25 pcs per tube
SM	PS2501-4SM, PS2501-4GRSM	Surface Mount	25 pcs per tube

CTR grade “L” available only for PS2501-1.

ORDER INFORMATION

PS2501-1X (UL and VDE Approvals)			
After PN	**PN**	**Description**	**Packing quantity**
None	PS2501-1X, PS2501-1XGR, PS2501-1XL	Standard DIP4	100 pcs per tube
G	PS2501-1XG, PS2501-1XGRG, PS2501-1XLG	10mm Lead Spacing	100 pcs per tube
SM	PS2501-1XSM, PS2501-1XGRSM, PS2501-1XLSM	Surface Mount	100 pcs per tube
SMT&R	PS2501-1XSMT&R, PS2501-1XGRSMT&R, PS2501-1XLSMT&R	Surface Mount Tape & Reel	1000 pcs per reel

PS2501-2X (UL and VDE Approvals)			
After PN	**PN**	**Description**	**Packing quantity**
None	PS2501-2X, PS2501-2XGR	Standard DIP8	50 pcs per tube
G	PS2501-2XG, PS2501-2XGRG	10mm Lead Spacing	50 pcs per tube
SM	PS2501-2XSM, PS2501-2XGRSM,	Surface Mount	50 pcs per tube
SMT&R	PS2501-2XSMT&R, PS2501-2XGRSMT&R	Surface Mount Tape & Reel	1000 pcs per reel

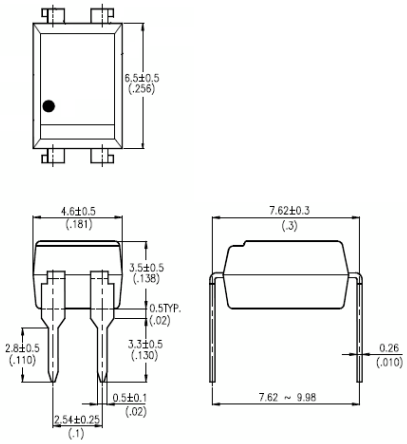
PS2501-4X (UL and VDE Approvals)			
After PN	**PN**	**Description**	**Packing quantity**
None	PS2501-4X, PS2501-4XGR,	Standard DIP16	25 pcs per tube
G	PS2501-4XG, PS2501-4XGRG	10mm Lead Spacing	25 pcs per tube
SM	PS2501-4XSM, PS2501-4XGRSM	Surface Mount	25 pcs per tube

CTR grade “L” available only for PS2501-1.

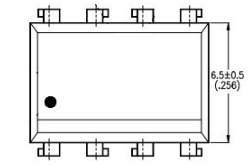
PACKAGE DIMENSIONS in mm (inch)

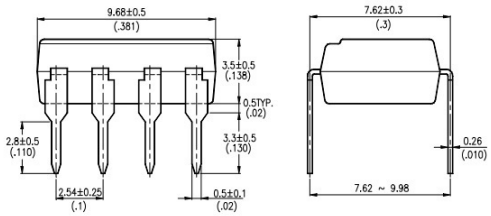
DIP

PS2501-1

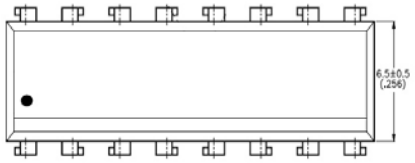


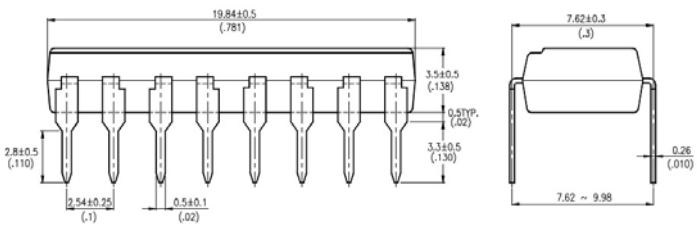
PS2501-2





PS2501-4

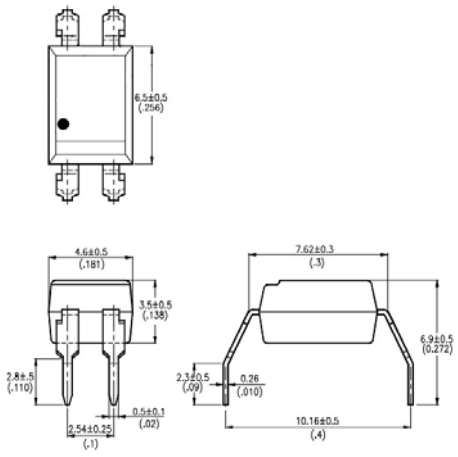




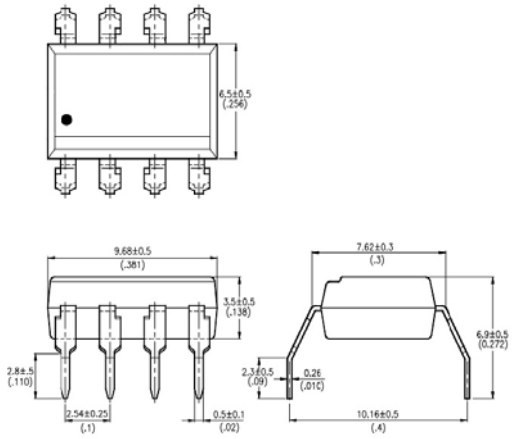
PACKAGE DIMENSIONS in mm (inch)

G Form

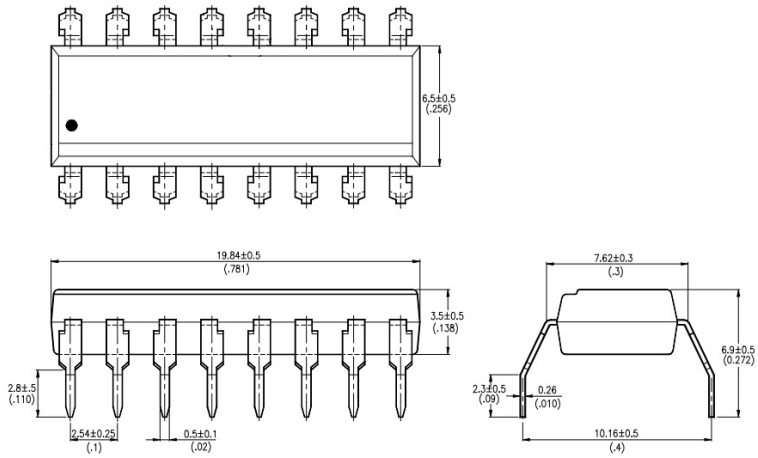
PS2501-1G



PS2501-2G



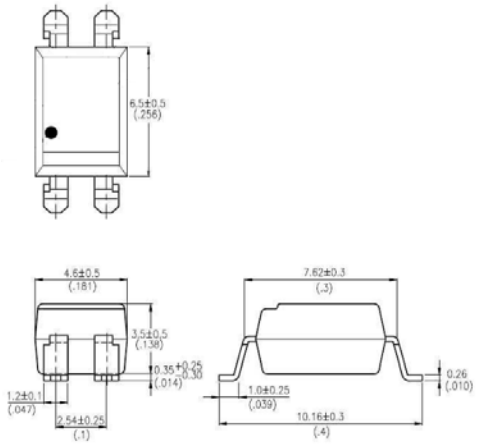
PS2501-4G



PACKAGE DIMENSIONS in mm (inch)

SMD

PS2501-1SM



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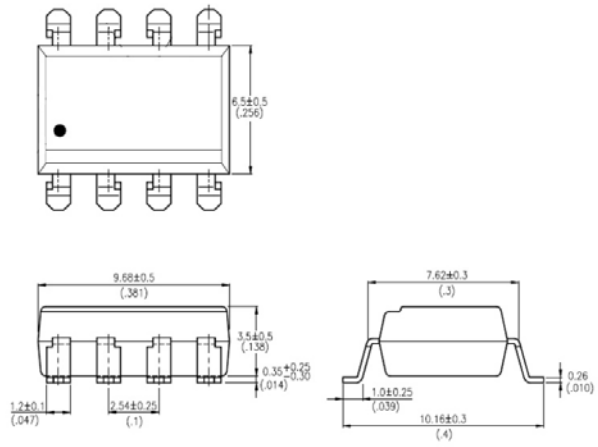
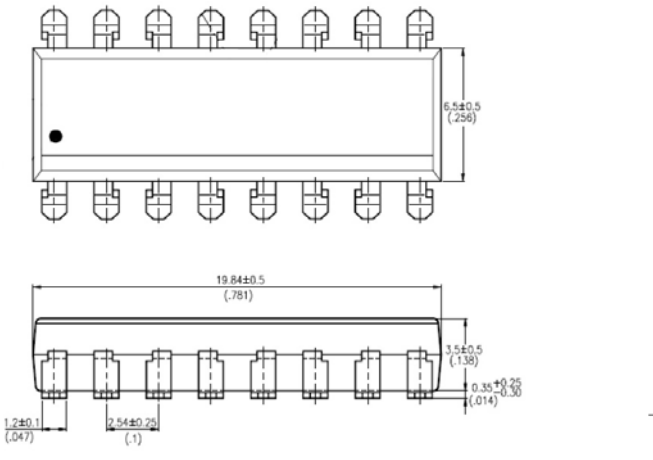
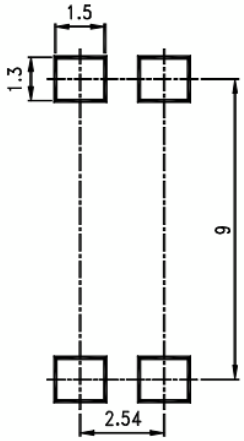


PS2501-4SM

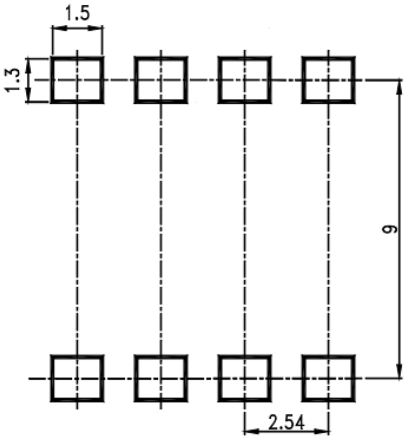


RECOMMENDED PAD LAYOUT FOR SMD (mm)

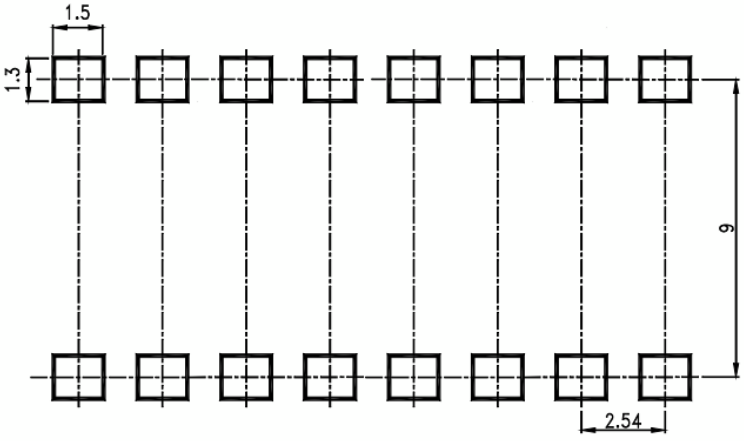
PS2501-1SM



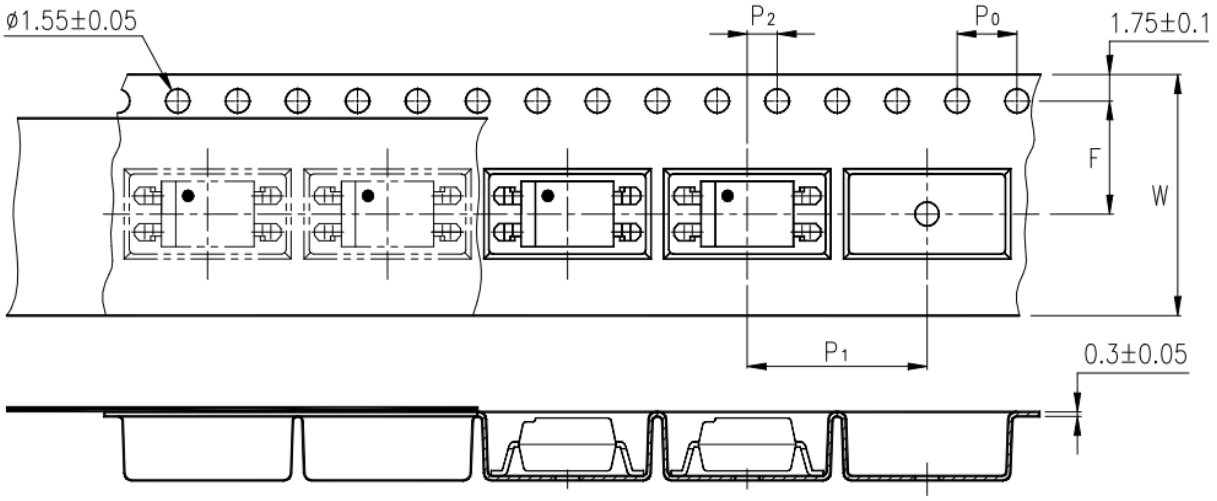
PS2501-2SM



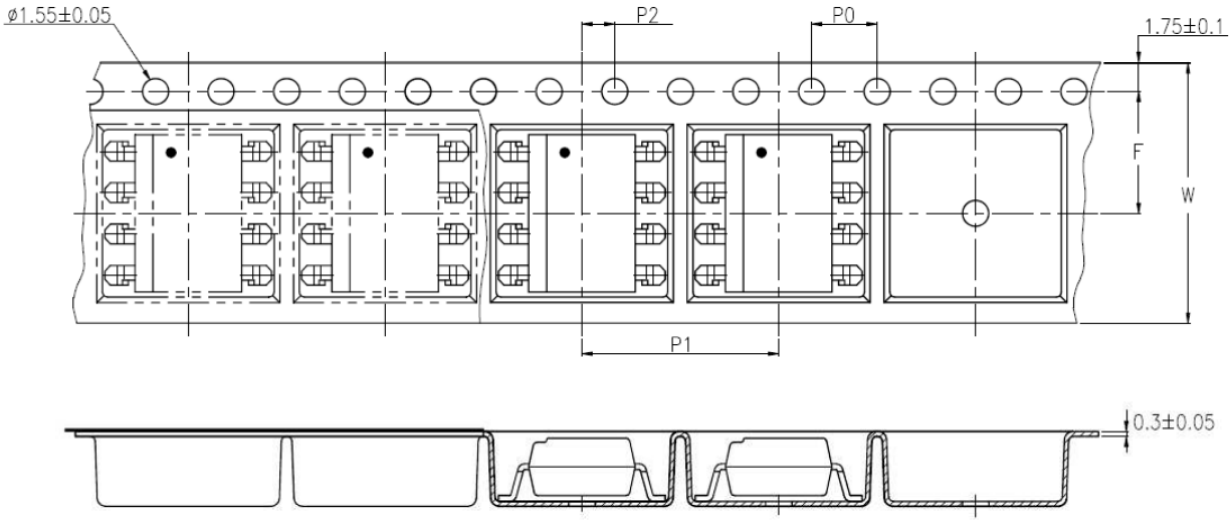
PS2501-4SM



TAPE AND REEL PACKAGING



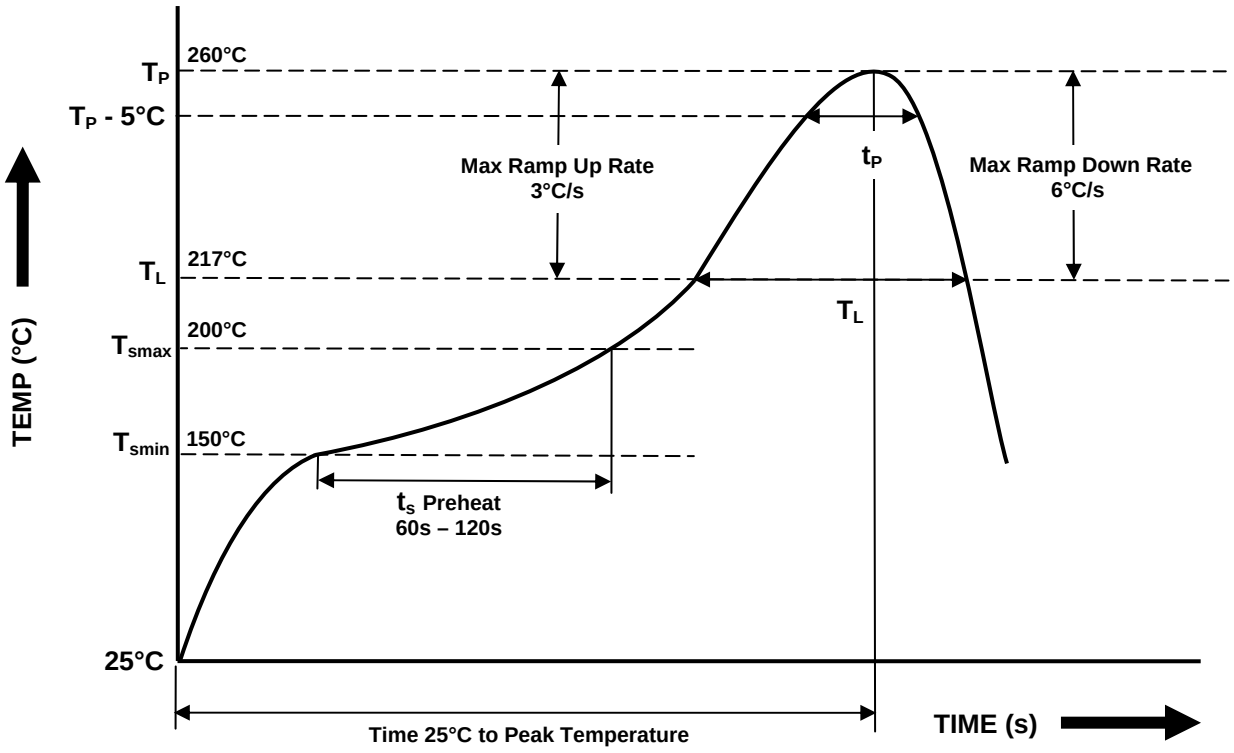
PS2501-1SMT&R



PS2501-2SMT&R

Description	Symbol	Dimensions in mm (inches)
Tape wide	W	16 ± 0.3 (.63)
Pitch of sprocket holes	P_0	4 ± 0.1 (.15)
Distance of compartment	F P_2	7.5 ± 0.1 (.295) 2 ± 0.1 (.079)
Distance of compartment to compartment	P_1	12 ± 0.1 (.472)

IR REFLOW SOLDERING TEMPERATURE PROFILE FOR SMD
(One Time Reflow Soldering is Recommended)



Profile Details	Conditions
Preheat - Min Temperature (T_{SMIN}) - Max Temperature (T_{SMAX}) - Time T_{SMIN} to T_{SMAX} (t_s)	 150°C 200°C 60s - 120s
Soldering Zone - Peak Temperature (T_P) - Time at Peak Temperature - Liquidous Temperature (T_L) - Time within 5°C of Actual Peak Temperature (T_P – 5°C) - Time maintained above T_L (t_L) - Ramp Up Rate (T_L to T_P) - Ramp Down Rate (T_P to T_L)	 260°C 10s max 217°C 30s max 60s - 100s 3°C/s max 6°C/s max
Average Ramp Up Rate (T_{smax} to T_P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max

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- For equipment/application where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc., please contact our sales representatives.

- When requiring a device for any ”specific” application, please contact our sales for advice.

- The contents described herein are subject to change without prior notice.

- Do not immerse device body in solder paste.

ISOCOM
COMPONENTS

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